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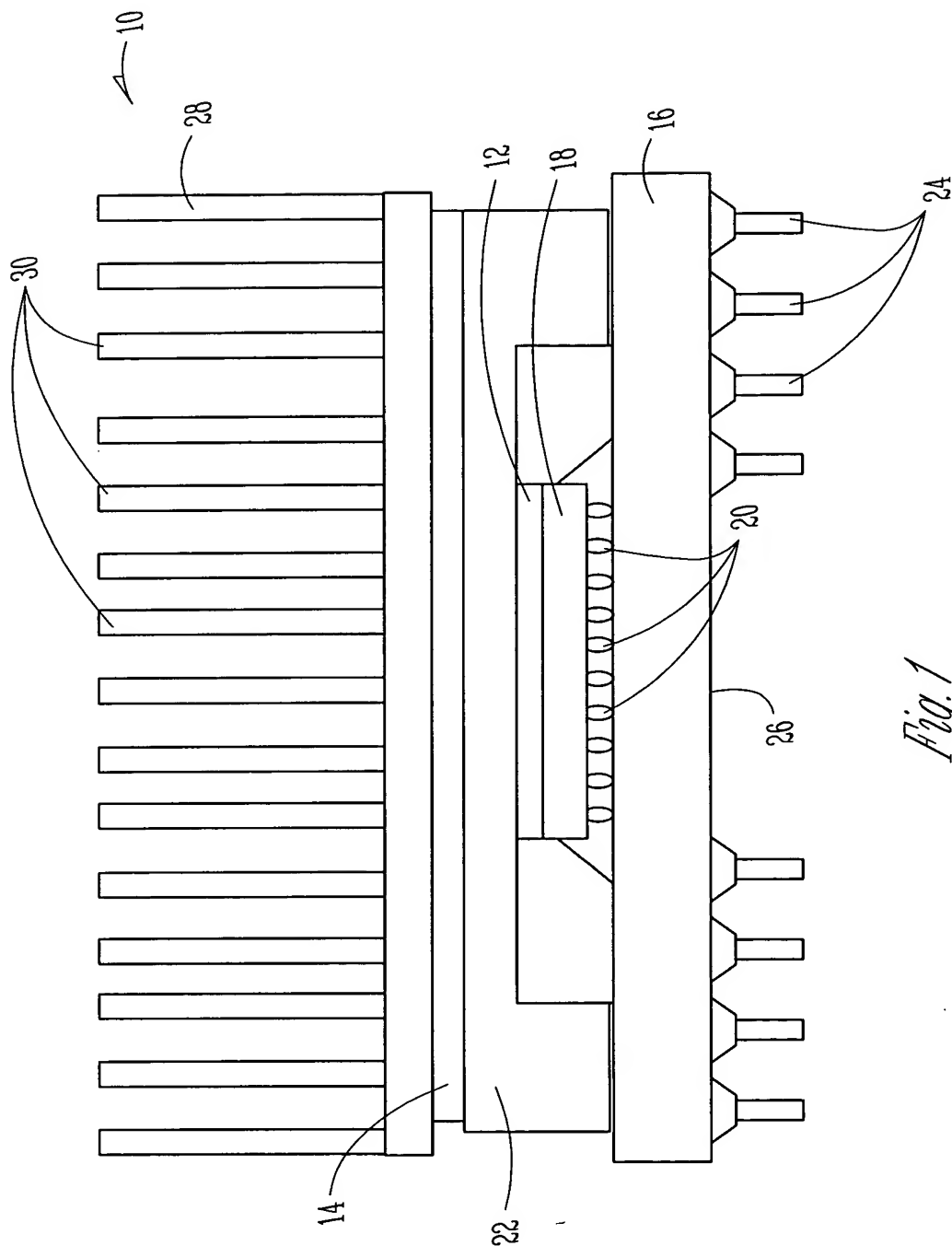


Fig. 1

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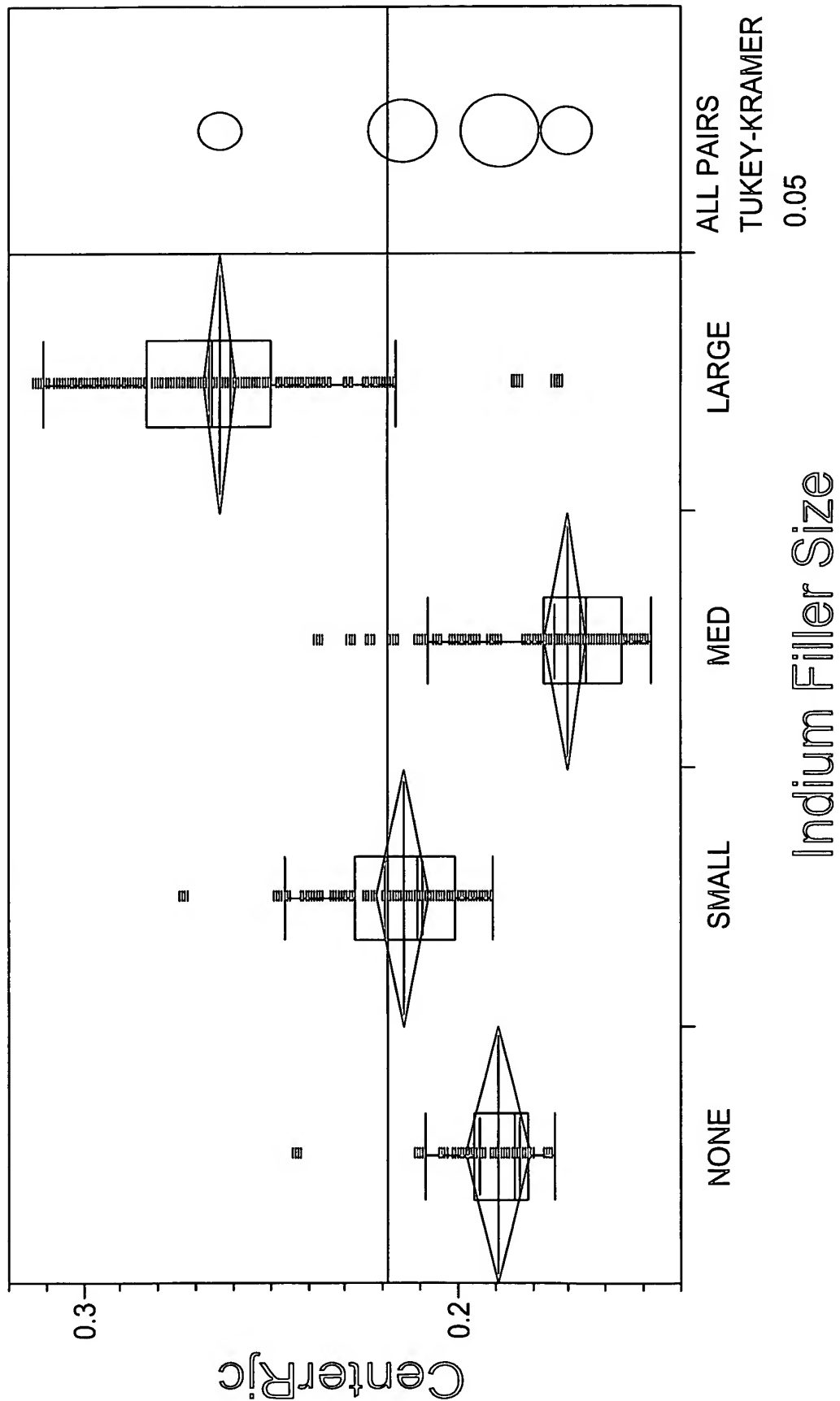


Fig. 2

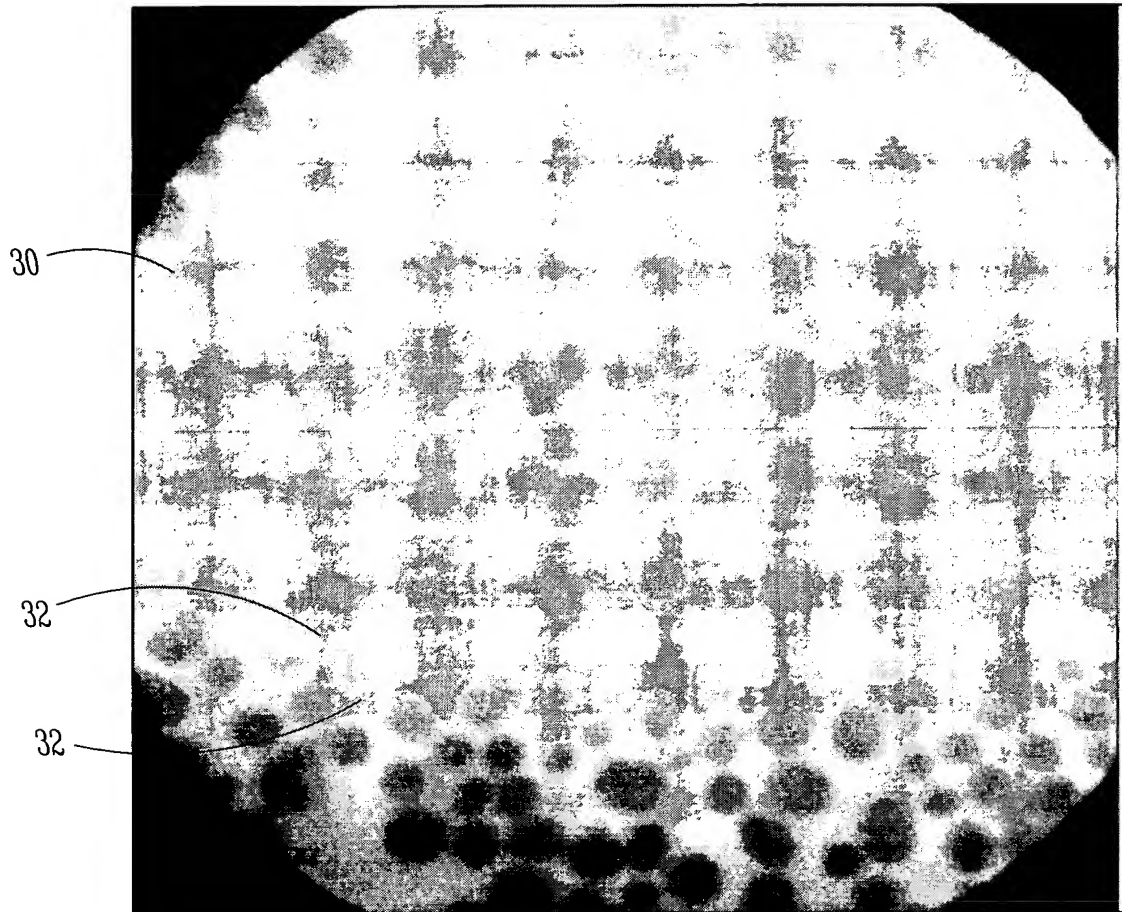


Fig. 3



TITLE: POLYMER SOLDER HYBRID INTERFACE MATERIAL WITH IMPROVED SOLDER FILLER PARTICLE SIZE AND MICROELECTRONIC PACKAGE APPLICATION

INVENTORS NAME: James C. Matayabas et al.

SERIAL NO.: 10/612328

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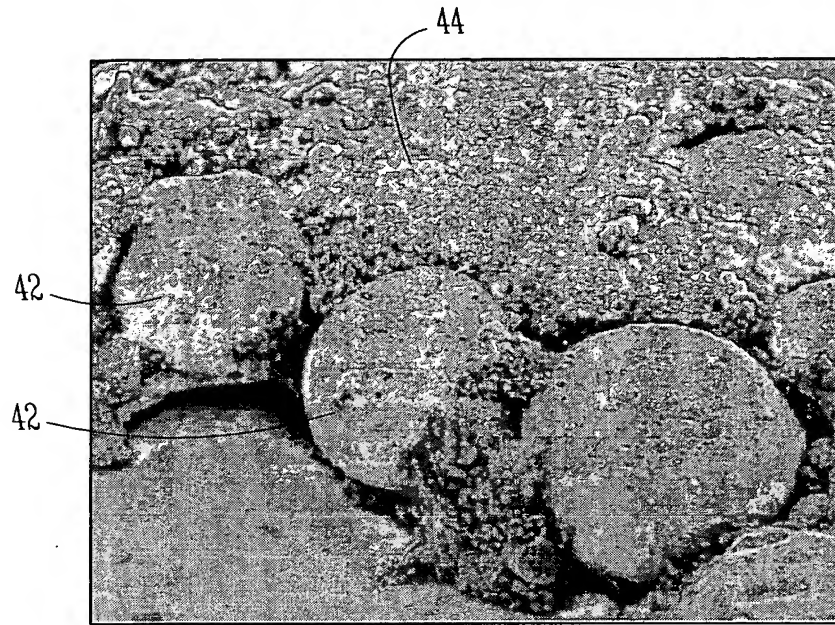


Fig. 4

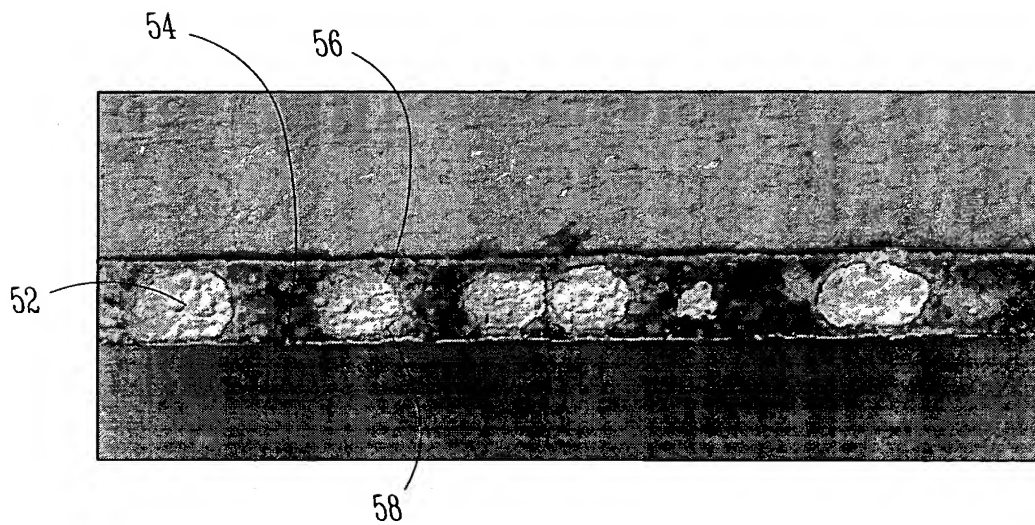


Fig. 5